

ATP04-4P-BM0X VARIANTS						
CONTACT PLATING	POTTING OR NOT IN RESERVOIR PART NUMBER					
GOLD	NO POTTING	ATP04-4P-BM01				
GOLD	POTTING	ATP04-4P-BM02				
TIN	NO POTTING	ATP04-4P-BM03				
TIN	POTTING	ATP04-4P-BM04				

	ATP04-4P-BM0X		X						
	PART NUMBER			DESCRIPTION			ITEM		
QUANTITY M				TERIALS LIST					
UNLESS OTHER		SIGN	ATURES	TURES DATE		$\overline{}$	mnho	no	I
	1) All dimensions are in metric(mm). 2) Tolerances are as follows: 1 PL DEC +0.30   L Fractions +1/64.	DRAWN:	IAN	12/OCT/21	1		mphe		ı
2 PL DEC ±0.30   Fractions ±1/64   Angles ±1°   3 PL DEC ±0.08	CHECKED:	SULLEN	12/OCT/21	Sine Systems - www.amphenol-sine.com					
3) Note reference = X		ENGINEER:				44724 Morley Drive			
MATERIAL SPECIFICATIONS:	APPROVAL:	TOMMY	13/OCT/21			Clinton Township, MI 480	136		
		CUSTOMER:			4 POSITION, PCB MOUNT RECEPTACLE, PINS, BOARDLOCK, ATP, STRAIGHT, SNAP FIT				
		THIS DRAWING IS SUPPLIED FOR INFORMATION ONLY, DESIGN FEATURES.							
PROCESS SPECIFICA	TIONS: SPECIFICATIONS AND PERFORMAN SHOWN HEREON ARE THE PROPET THE AMPHENOL CORPORATION. NO OF REPRODUCTION ARE IMPLIED. DIMENSIONS ARE SIR BILET TO NO!		ORMANCE DATA PROPERTY OF TION. NO RIGHTS PLIED. ALL TO NORMAL	В	C-	ATP04-4P-I	BM0X	A2	
NEXT ASS'Y:		MANUFACTURING VARIATIONS.		SCALE: NO	ONE		sнеет <b>1</b>	or <b>1</b>	

DATE

27/SEP/21

12/OCT/21

10.15

BY

2x Ø3.30

4x Ø2.60

Ø3.20

APPR

4 POS,PCB RECEPT,PINS,BOARDLOCK,ATP,STRT,SNAP FIT

ATP04-4P-BM0X

REV: A2 SH: 1

IAN TOMMY

IAN TOMMY

3.4 INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 25°C.
3.5 MOISTURE RESISTANCE:
IP68(IM OF WATER FOR A PERIOD OF 24 HOURS, MATED
CONDITION);
IP69K(MATED CONDITION).
3.6 MATING CYCLE DURABILITY: 100 CYCLES

- 3.7 RoHS COMPLIANT
- 4. MATING PART: ATP06-4S\* PLUG (\* = ALL MODIFICATIONS)

3.2 OPERATING TEMPERATURE: -55°C TO +125°C 3.3 DIELECTRIC WITHSTANDING VOLTAGE: LESS THAN 2 MILLIAMPS CURRENT LEAKAGE @ 1500 VOLTS AC. 3.4 INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 25°C.

5. ALL DIMENSIONS ARE FOR REFERENCE USE ONLY.